L Number	Hits	Search Text	DB	Time stamp
1	7472	430/30 or 257/273 or 714/724	USPAT;	2004/08/04 17:16
-			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
2	5786600	photolithography system	USPAT;	2004/08/04 17:16
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
3	72481	photolithography tool and (stage with	IBM_TDB USPAT;	2004/08/04 17:18
3	72401	semiconductor wafer near1 mounted)	US-PGPUB;	2004/08/04 17:18
		Semiconductor water hearr mounted,	EPO; JPO;	
			DERWENT;	
			IBM TDB	
4	2480858	pre-determined image	USPAT;	2004/08/04 17:19
		-	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
_			IBM_TDB	
5	371569	mov\$3 near1 stage with automatically focus	USPAT;	2004/08/04 17:21
		near1 pre-determined image near5	US-PGPUB;	
		semiconductor wafer	EPO; JPO;	
			DERWENT;	
6	21003	(pre-determined image) and	IBM_TDB	2004/00/04 17:01
"	21003	(pre-determined image) and (photolithography tool and (stage with	USPAT; US-PGPUB;	2004/08/04 17:21
		semiconductor wafer near1 mounted))	EPO; JPO;	
		Semiconductor water hearr mounted,,	DERWENT;	
			IBM TDB	
7	20901	(photolithography system) and	USPAT;	2004/08/04 17:21
-		((pre-determined image) and	US-PGPUB;	
		(photolithography tool and (stage with	EPO; JPO;	
		semiconductor wafer nearl mounted)))	DERWENT;	
		l	IBM_TDB	
8	792	, , ,	USPAT;	2004/08/04 17:22
		focus near1 pre-determined image near5	US-PGPUB;	
		semiconductor wafer) and	EPO; JPO;	
		((photolithography system) and	DERWENT;	
		((pre-determined image) and (photolithography tool and (stage with	IBM_TDB	
]		semiconductor wafer nearl mounted))))		
9	8	(430/30 or 257/273 or 714/724) and ((mov\$3	USPAT;	2004/08/04 17:23
]		nearl stage with automatically focus nearl	US-PGPUB;	-55.,55,64 17,25
		pre-determined image near5 semiconductor	EPO; JPO;	
		wafer) and ((photolithography system) and	DERWENT;	
		((pre-determined image) and	IBM_TDB	
		(photolithography tool and (stage with		
1,0	1675547	semiconductor wafer near1 mounted)))))		
10	1575547	automation host computer	USPAT;	2004/08/04 17:26
			US-PGPUB;	
]			EPO; JPO;	
			DERWENT; IBM TDB	
11	831	poll\$3 and (photolithography tool with	USPAT;	2004/08/04 17:27
	331	data near2 logged movement near2 stage)	US-PGPUB;	2004/00/04 17.27
			EPO; JPO;	ļ
			DERWENT;	
			IBM TDB	
13	26277	(automation host computer) and (analyz\$3	USPAT;	2004/08/04 17:30
		nearl data)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
14	1107007	companed and Ideba with and the	IBM_TDB	0004/00/04 == ==
14	1127027	<pre>compar\$3 and (data with predetermined error condition\$1)</pre>	USPAT;	2004/08/04 17:29
		error condition\$1)	US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
L		<u> </u>	TOM IND	

15	17855	((automation host computer) and (analyz\$3 nearl data)) and (compar\$3 and (data with	USPAT; US-PGPUB;	2004/08/04 17:29
		predetermined error condition\$1))	EPO; JPO; DERWENT;	
17	4	(((automation host computer) and (analyz\$3 nearl data)) and (compar\$3 and (data with predetermined error condition\$1))) and ((mov\$3 nearl stage with automatically focus nearl pre-determined image near5 semiconductor wafer) and ((photolithography system) and ((pre-determined image) and (photolithography tool and (stage with semiconductor wafer nearl mounted)))))	IBM_TDB USPAT	2004/08/04 17:31

L Number	Hits	Search Text	DB	Time stamp
1	7472	<u> </u>	USPAT;	2004/08/04 17:16
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
2	5786600	nhotolithography and a	IBM_TDB	2004/00/04 17:16
2	3788800	photolithography system	USPAT; US-PGPUB;	2004/08/04 17:16
1			EPO; JPO;	
			DERWENT;	
			IBM TDB	
3	72481	photolithography tool and (stage with	USPAT;	2004/08/04 17:18
		semiconductor wafer near1 mounted)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
1.			IBM_TDB	
4	2480858	pre-determined image	USPAT;	2004/08/04 17:19
			US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
5	371569	mov\$3 near1 stage with automatically focus	USPAT:	2004/08/04 17:21
-		near1 pre-determined image near5	US-PGPUB;	
		semiconductor wafer	EPO; JPO;	
			DERWENT;	
			IBM_TDB	İ
6	21003	(pre-determined image) and	USPAT;	2004/08/04 17:21
		(photolithography tool and (stage with	US-PGPUB;	l
		semiconductor wafer near1 mounted))	EPO; JPO;	
			DERWENT;	
7	20901	(photolithography system) and	IBM_TDB USPAT;	2004/08/04 17:21
'	20301	((pre-determined image) and	US-PGPUB;	2004/08/04 17:21
		(photolithography tool and (stage with	EPO; JPO;	
		semiconductor wafer near1 mounted)))	DERWENT;	
			IBM_TDB	i
8	792	,	USPAT;	2004/08/04 17:22
		focus near1 pre-determined image near5	US-PGPUB;	
		semiconductor wafer) and	EPO; JPO;	
		((photolithography system) and ((pre-determined image) and	DERWENT; IBM TDB	
		(photolithography tool and (stage with	1514-105	
		semiconductor wafer nearl mounted))))		
10	1575547	automation host computer	USPAT;	2004/08/04 17:26
		<u>-</u>	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	001	mall 62 and /mb-b-124b	IBM_TDB	000440045
11	831	poll\$3 and (photolithography tool with	USPAT;	2004/08/04 17:27
		data near2 logged movement near2 stage)	US-PGPUB; EPO; JPO;	
j l			DERWENT;	
			IBM TDB	
13	26277	(automation host computer) and (analyz\$3	USPAT;	2004/08/04 17:30
		nearl data)	US-PGPUB;	
1			EPO; JPO;	
]			DERWENT;	
14	1127027	compane? and (data with analytical)	IBM_TDB	0004/00/01 15 55
**	1127027	compar\$3 and (data with predetermined error condition\$1)	USPAT;	2004/08/04 17:29
		CLICE CONGICIONAL/	US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM TDB	
15	17855	((automation host computer) and (analyz\$3	USPAT;	2004/08/04 17:29
		nearl data)) and (compar\$3 and (data with	US-PGPUB;	
j		predetermined error condition\$1))	EPO; JPO;	
			DERWENT;	
L			IBM_TDB	

17	4	(((automation host computer) and (analyz\$3 nearl data)) and (compar\$3 and (data with predetermined error condition\$1))) and ((mov\$3 nearl stage with automatically focus nearl pre-determined image near5 semiconductor wafer) and ((photolithography system) and ((pre-determined image) and (photolithography tool and (stage with semiconductor wafer nearl mounted))))	USPAT	2004/08/04 17:47
9	8		USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 17:54
18	21689		USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/04 17:55
19	4	257/273 or 714/724) and ((mov\$3 near1 stage with automatically focus near1 pre-determined image near5 semiconductor wafer) and ((photolithography system) and ((pre-determined image) and (photolithography tool and (stage with	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 17:56
20	4	semiconductor wafer nearl mounted))))) (355/? or 430/? or 359/?) and ((355/? or 430/? or 359/?) and ((430/30 or 257/273 or 714/724) and ((mov\$3 nearl stage with automatically focus nearl pre-determined image near5 semiconductor wafer) and ((photolithography system) and ((pre-determined image) and (photolithography tool and (stage with semiconductor wafer nearl mounted))))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 17:57
21	880	(355/? or 430/? or 359/?) and (430/30 or 257/273 or 714/724)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/04 17:57
22	4	((355/? or 430/? or 359/?) and (430/30 or 257/273 or 714/724)) and ((mov\$3 near1 stage with automatically focus near1 pre-determined image near5 semiconductor wafer) and ((photolithography system) and ((pre-determined image) and (photolithography tool and (stage with semiconductor wafer near1 mounted)))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 17:58